Product Change Notification - KSRA-07LEDG378

**Date:**
25 Jan 2018

**Product Category:**
Linear Op Amps; 8-bit PIC Microcontrollers; Interface- Passive-Keyless-Entry Analog Front End; Touch Controllers; Interface- Infrared Products; USB Bridge; Interface- Controller Area Network (CAN); Successive Approximation Register (SAR) A/D Converters; Sigma - Delta A/D Converters; Digital Potentiometers; System D/A Converters; Linear Comparators; Linear Selectable Gain Amplifiers; Linear Programmable Gain Amplifiers; Memory; Power MOSFET Drivers; Interface- LIN Transceiver; Ionization Smoke Detector Front Ends; Piezoelectric Horn Drivers; Charge Pump DC-to-DC Converters

**Notification subject:**
CCB 3140 and CCB 3140.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products available in 8L and 14L SOIC package at MTAI assembly site.

**Notification text:**

**PCN Status:**
Final notification

**PCN Type:**
Manufacturing Change

**Microchip Parts Affected:**
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

**NOTE:** For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**
Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products available in 8L and 14L SOIC package at MTAI assembly site.

**Pre Change:**
Using Palladium coated copper wire (PdCu) bond wire
**Post Change:**
Using palladium coated copper with gold flash (CuPdAu) bond wire

**Pre and Post Change Summary:**

<table>
<thead>
<tr>
<th></th>
<th>Pre Change</th>
<th>Post Change</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Assembly Site</strong></td>
<td>Microchip Technology Thailand (HQ) / MTAI</td>
<td>Microchip Technology Thailand (HQ) / MTAI</td>
</tr>
<tr>
<td><strong>Wire material</strong></td>
<td>PdCu Wire</td>
<td>CuPdAu Wire</td>
</tr>
<tr>
<td><strong>Die attach material</strong></td>
<td>8390A</td>
<td>8390A</td>
</tr>
<tr>
<td><strong>Molding compound material</strong></td>
<td>G600V</td>
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</tr>
<tr>
<td><strong>Lead frame material</strong></td>
<td>CDA194</td>
<td>CDA194</td>
</tr>
</tbody>
</table>

**Impacts to Data Sheet:**
None

**Change Impact:**
None

**Reason for Change:**
To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire

**Change Implementation Status:**
In Progress

**Estimated First Ship Date:**
February 22, 2018 (date code: 1808)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

<table>
<thead>
<tr>
<th></th>
<th>January 2018</th>
<th>February 2018</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Workweek</strong></td>
<td>01 02 03 04 05 06 07 08</td>
<td></td>
</tr>
<tr>
<td><strong>Qual Report Availability</strong></td>
<td>X</td>
<td></td>
</tr>
<tr>
<td><strong>Final PCN Issue Date</strong></td>
<td>X</td>
<td></td>
</tr>
<tr>
<td><strong>Estimated</strong></td>
<td></td>
<td>X</td>
</tr>
</tbody>
</table>
Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#{number}_Qual Report.

Revision History:
January 25, 2018: Issued final notification.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

Attachment(s):
PCN_KSRA-07LEDG378_Affected_CPN.pdf
PCN_KSRA-07LEDG378_Qual_Report.pdf
PCN_KSRA-07LEDG378_Affected_CPN.xlsx

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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